

General Description

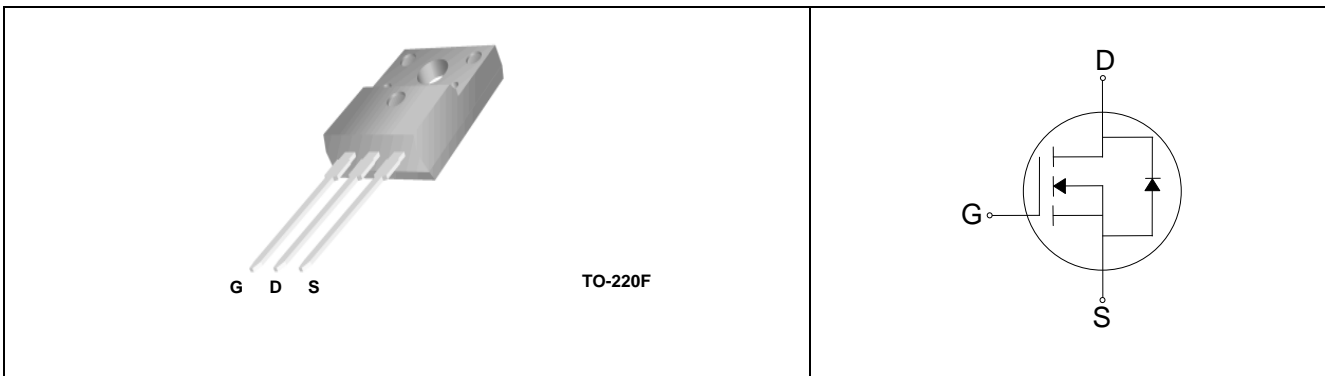
This Power MOSFET is produced using Maple semi's Advanced Super-Junction technology.

This advanced technology has been especially tailored to minimize conduction loss, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for AC/DC power conversion

Features

- 11A, 650V, RDS(on) typ.= 330mΩ@VGS =10 V
- Low gate charge (typical 17.5nC)
- High ruggedness
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings

TC = 25°C unless otherwise noted

| Symbol | Parameter | SLF65R380SS | Units |
|----------|---|---------------------------|-------|
| VDSS | Drain-Source Voltage | 650 | V |
| ID | Drain Current | - Continuous (TC = 25°C) | 11 |
| | | - Continuous (TC = 100°C) | 5.5 |
| IDM | Drain Current - Pulsed (Note 1) | 33 | A |
| VGSS | Gate-Source Voltage | ± 30 | V |
| EAS | Single Pulsed Avalanche Energy (Note 2) | 125 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | 50 | V/ns |
| PD | Power Dissipation (TC = 25°C) | | 31 |
| | | - Derate above 25°C □ | 0.25 |
| TJ, TSTG | Operating and Storage Temperature Range | -55 to +150 | °C |
| TL | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | | 300 |

*Drain current limited by maximum junction temperature.

Thermal Characteristics

| Symbol | Parameter | Value | Units |
|--------|---|-------|-------|
| RθJC | Thermal Resistance, Junction-to-Case | 4.03 | °C/W |
| RθJA | Thermal Resistance, Junction-to-Ambient | 62.5 | °C/W |

Electrical Characteristics (TC = 25 °C unless otherwise noted)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|-------------------------------|---|--------------------------------|-----|------|------|-------|
| Off Characteristics | | | | | | |
| BVDSS | Drain-Source Breakdown Voltage | VGS = 0V, ID = 250uA, TJ=25°C | 650 | - | - | V |
| | | VGS = 0V, ID = 250uA, TJ=150°C | - | 650 | - | V |
| Δ BVDSS Δ TJ | Breakdown Voltage Temperature coefficient | ID = 250uA, referenced to 25°C | - | 0.65 | - | V/°C |
| IDSS | Drain-Source Leakage Current | VDS =650V, VGS = 0V | - | - | 1 | uA |
| | | VDS =520V, TC = 125 °C | - | - | 10 | uA |
| IGSS | Gate-Source Leakage, Forward | VGS = 30V, VDS = 0V | - | - | 100 | nA |
| | Gate-source Leakage, Reverse | VGS = -30V, VDS = 0V | - | - | -100 | nA |

On Characteristics

| | | | | | | |
|---------|---|-----------------------|-----|------|------|----------|
| VGS(th) | Gate Threshold Voltage | VDS = VGS, ID = 250uA | 2.5 | - | 4.5 | V |
| RDS(ON) | Static Drain-Source On-state Resistance | VGS =10 V, ID = 3.2A | - | 0.33 | 0.38 | Ω |

Dynamic Characteristics

| | | | | | | |
|------|------------------------------|------------------------------|---|-----|------|----|
| Ciss | Input Capacitance | VGS =0 V, VDS =25V, f = 1MHz | - | 900 | 1170 | pF |
| Coss | Output Capacitance | | - | 54 | 70 | |
| Crss | Reverse Transfer Capacitance | | - | 7.0 | 9.5 | |

Dynamic Characteristics

| | | | | | | |
|---------|----------------------------------|-------------------------------------|---|------|-----|----|
| td(on) | Turn-on Delay Time | VDD =320V, ID =11A, RG =25 Ω | - | 30 | 70 | nS |
| tr | Rise Time | | - | 17 | 44 | |
| td(off) | Turn-off Delay Time | | - | 70 | 150 | |
| tf | Fall Time | | - | 17 | 44 | |
| Qg | Total Gate Charge | VDS =480V, VGS =10V, ID =25A | - | 17.5 | 23 | nC |
| Qgs | Gate-Source Charge | | - | 5.0 | - | |
| Qgd | Gate-Drain Charge(Miller Charge) | | - | 5.5 | - | |

Source-Drain Diode Ratings and Characteristics

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit. |
|--------|---|---------------------------------|------|------|------|-------|
| IS | Maximum Continuous Drain-Source Diode Forward Current | | - | - | 11 | A |
| ISM | Maximum Pulsed Drain-Source Diode Forward Current | | - | - | 33 | |
| VSD | Diode Forward Voltage | IS =25A, VGS =0V | - | - | 1.4 | V |
| trr | Reverse Recovery Time | IS =25A, VGS=0V, dIF/dt=100A/us | - | 220 | - | nS |
| Qrr | Reverse Recovery Charge | | - | 2.0 | - | uC |

NOTES

1. Repeativity rating : pulse width limited by junction temperature
2. IAS =2.1A, VDD = 50V, RG = 25 Ω , Starting TJ = 25°C
3. ISD \leq ID, di/dt \leq 200A/us, VDD \leq BVDSS, Starting TJ = 25°C
4. Pulse Test : Pulse Width \leq 300us, Duty Cycle \leq 2%
5. Essentially independent of operating temperature.

TYPICAL ELECTRICAL CHARACTERISTICS

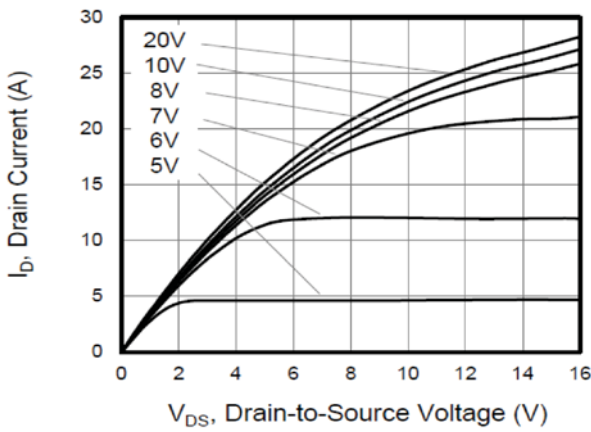


Figure 1. On Region Characteristics

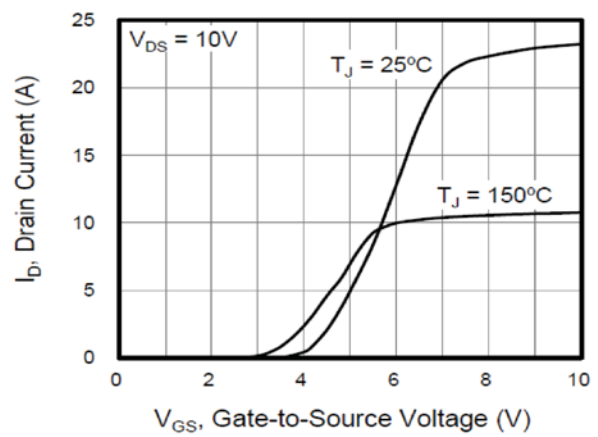


Figure 2. Transfer Characteristics

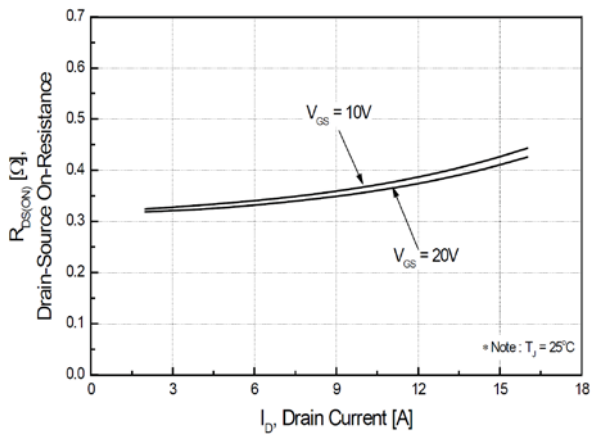


Figure 3. On Resistance Variation vs Drain Current and Gate Voltage

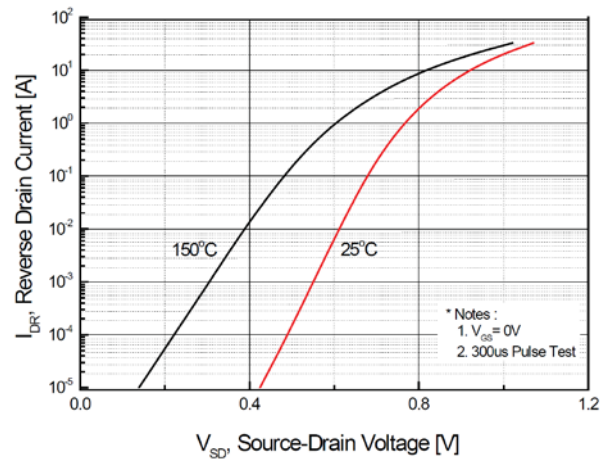


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

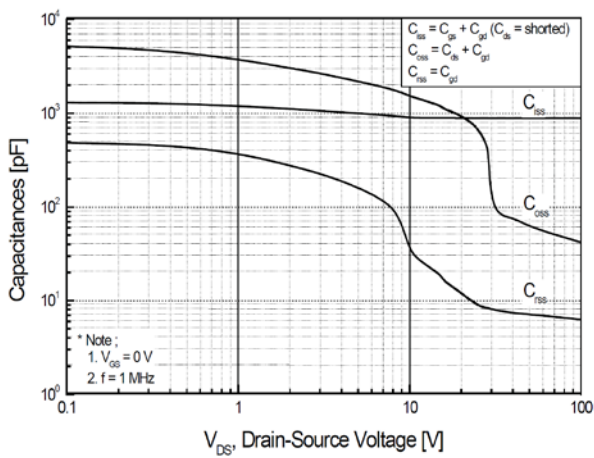


Figure 5. Capacitance Characteristics

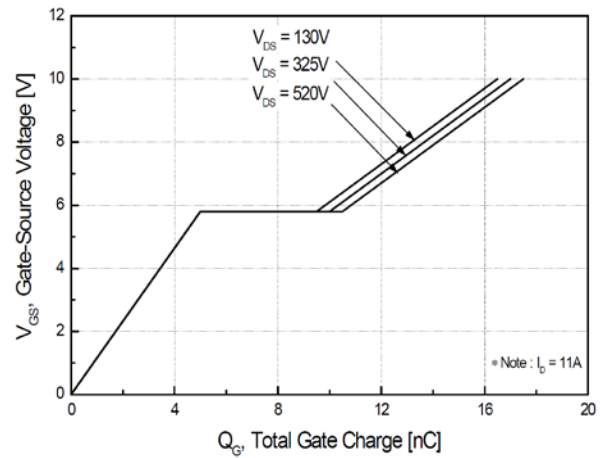


Figure 6. Gate Charge Characteristics

TYPICAL ELECTRICAL CHARACTERISTICS

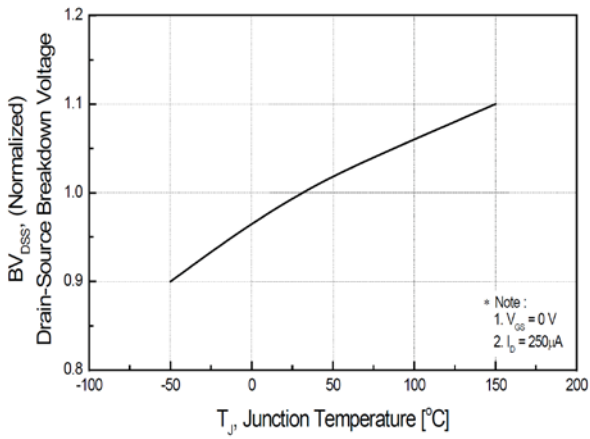


Figure 7. Breakdown Voltage Variation vs Temperature

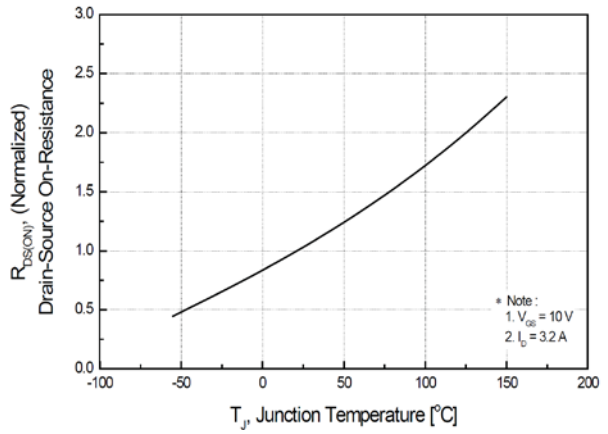


Figure 8. On-Resistance Variation VS Temperature

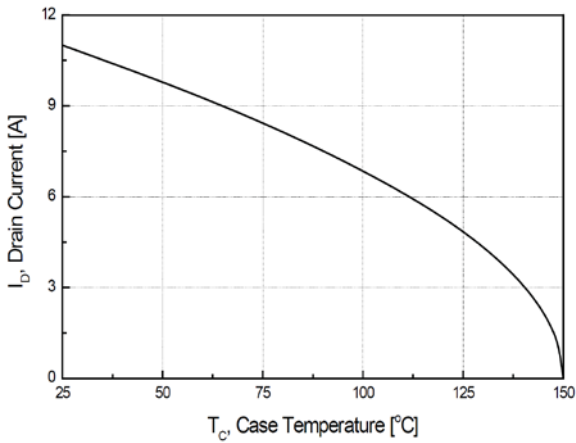


Figure 9. Maximum Safe Operating Area

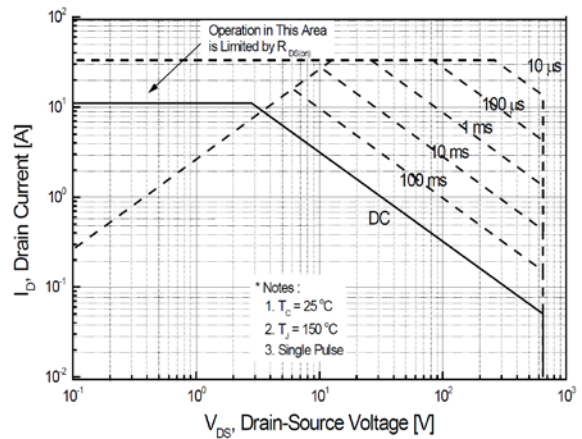


Figure 10. Maximum Drain Current vs Case Temperature

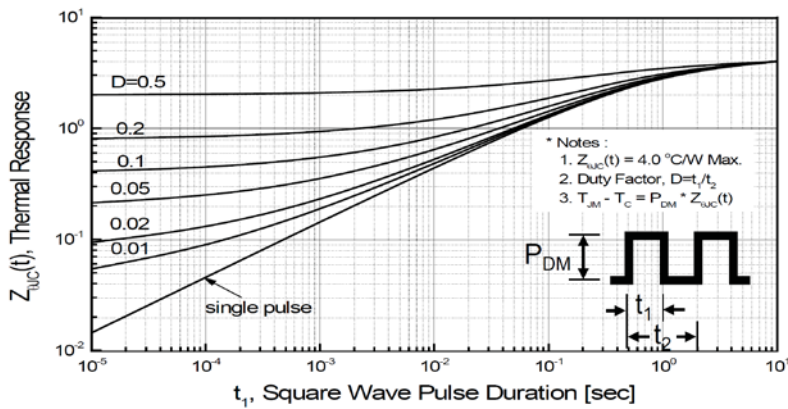
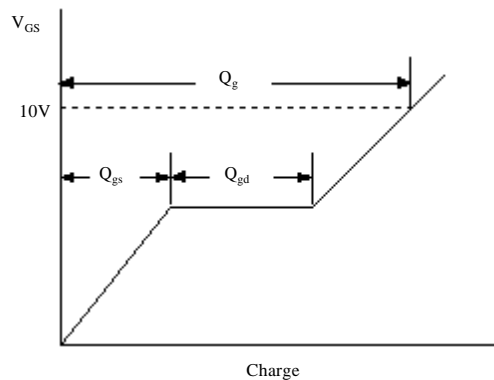
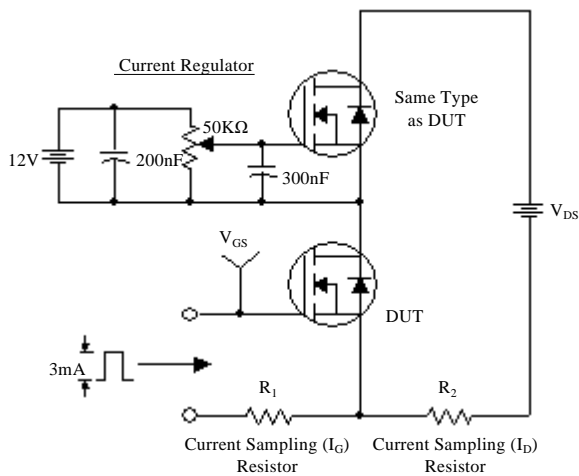
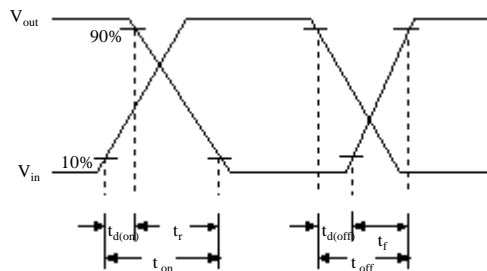
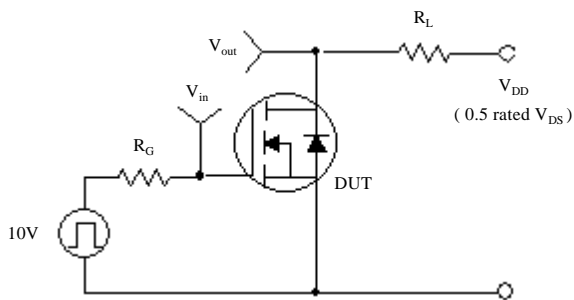


Figure 11. Transient Thermal Response Curve

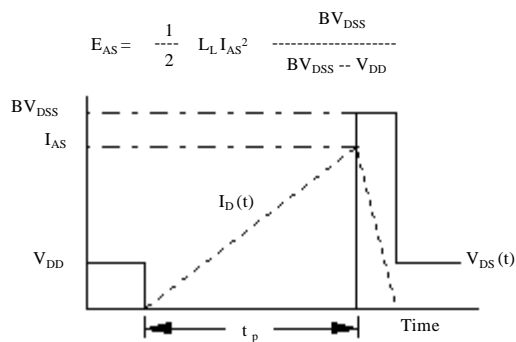
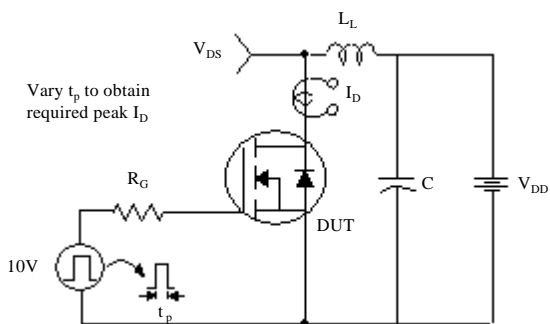
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

